

366 Ball LPDDR4 PoP Interposer Interconnect for the MA5000 Memory Analyzer

- Interconnect for 366 Ball LPDDR4
 Package on Package (PoP)
 - 15mm x 15mm
 - 4 x 16 Data Width
 - 0.5mm Pitch
- Optimized for JEDEC Compliance
- Socketed Design for Easy Install
- Can be Soldered directly to your SOC
- Use with existing Embedded/Mobile Designs
- Probed at the BGA Pads for Maximum Signal Integrity
- Use with Nexus Memory Analyzer (also compatible with Tektronix TLA)



LPDDR4 component interposers for applications requiring optimal digital validation of LPDDR4 targets. These interposers allow for real time compliance analysis with an MA5000 or use with a traditional logic analyzer. Scope probe points are also available for additional visibility.



MA5000 Real Time JEDEC Protocol Compliance Analysis

- Real time JEDEC compliance analysis of the LPDDR4 bus using the 366 ball interposer (See MA5000 Datasheet for more information)
- MA5000 includes an integrated logic analyzer for use in addition to the real time JEDEC compliance validation
- Programmable MA input enables accurate sample point setting and probe termination option to ground or VTT.
- Supports the fastest LPDDR4 speeds specified in JEDEC
- Optimize your design using MA features

The PoP Challenge

Low Power DDR4 (LPDDR4) memory components are expanding rapidly in the market providing low power, high bandwidth, high density memory solutions. The Package on Package version results in target space saving but introduces significant roadblocks for test/debug and analysis of the memory interface.





Figure 1 - Side view (photo) of PoP memory soldered on to a processor

Premier Component Interposer Design

Optimal LPDDR4 validation requires analysis of the LPDDR4 signals, as seen by the memory components. This allows for the highest confidence that the captured signals are representative of the signals on the target. Nexus Technology component interposers allow for logic analyzer probing of the LPDDR4 signals at the memory components BGA balls.

LPDDR4 BGA Component installation

The interposer can be ordered with a socket on the interposer for easy BGA memory component installation and removal. These sockets allow for the quick swapping and testing of different memory components on the interposer. The Sockets quick Start Guide provides more information.

Logic Analyzer Component Interposer Hardware

Connection to the MA instrument is enabled by using LPDDR4 Memory Component Interposers. These controlled impedance, matched trace length interposers provide visibility for digital validation using a logic analyzer. These interposers are also compatible with the Tektronix TLA.

Mechanical Dimensions



Product Configurations

Nomenclature	Interposer Type	Data Width	Component Sockets Included
NEX-LP4POP366CA	MA5000/TLA	4 Channel x16	No
NEX-LP4POP366CA-SK	MA5000/TLA	4 Channel x16	Yes

Optional LPDDR4 366 Ball Riser

Nomenclature	Solder Balls Added	Quantity of Riser
NEX-RSRLPDDR4366	No	1

Further Information

Please contact us by telephone, email or mail as listed below. Normal business hours are 9:00 – 5:00 EST.

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